**Position Title:** Package Assembly Operator – Many Shifts

**Department:** Manufacturing

**Position # or Level:** QPT OPER

**Employment Status:** Regular Full Time

**Reports to:** Manufacturing Manager

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<th>% Travel Required</th>
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### Position Summary:
QP Technologies (formerly Quik-Pak) is a leading provider of microelectronic packaging and assembly, wafer preparation, and substrate design and development services and our service offerings enable our customers to target a range of end markets, including commercial, RF, power, industrial, automotive, medical and mil-aero. As a Package/Assembly Operator, you will work on some of the most advanced hardware technology in the world in an atmosphere that is stimulating, team spirited, and customer focused.

### Essential Duties:
- Responsible for packaging/assembly of semiconductor devices (training disciplines include Wire Bonding, Silicon Wafer Prep, Silicon Die Attach, Plastic Encapsulation/Lid Seal, Surface Mount, Plastic Package Decapsulation and more).
- Meet production, quality, and efficiency standards.
- Work under a microscope for extended periods, at times
- Read and follow written as well as verbal work instructions

### Minimum Qualifications:
- **Education, Experience & Citizenship Requirements**
  - High School diploma or equivalent
  - Able to work in a cleanroom environment and follow strict gowning and ESD (ElectroStatic Discharge) protocols.
  - Able to use microscopes and various other semiconductor equipment.
  - Must have excellent hand dexterity.
  - Must be able to read and write English.
  - **Must be a US Citizen or legal Permanent Resident.**

### Key Competencies
- Detail oriented and exhibit a high level of accuracy.
- Team player that takes pride in their work – yes!!

### Preferred Skills:
Prior experience working on microelectronic devices or working in an ISO certified and/or ITAR registered environment is highly preferred.